GAP PAD Dispensable

FT_TDG_080_AB_63

Our Thermal Foams also called TDG is a low volatility LV silicone space filler dispensable in 2 parts that is filled with thermally conductive fillers. After hardening under heat the system remains elastic. The TDG_080_AB_NS is characterized by very good dielectric and mechanical properties and is suitable to compensate for extreme tolerances and spaces in non-planar systems. Indeed, it is a GOOD thermal conductor of 8W/ mK, with a good thermal resistance thus facilitating the transfer of heat and also has excellent electrical insulation. All our TDG are UL 94 V0 certified.

Application areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR ll Module, etc.

Technical characteristics

Features	Unit	TDG_080_AB_NS
Thickness	mm	-
Density	g/cm^3	3
Color	-	Yellow
Hardness	Shore 00	-
Packaging	//	Syringe/jar
Viscosity	PAS	430
Hardening temsp	25 /100°C	-
Outgassing	TML	-
Thermal Conductivity	W/mK	8
Temperature	°C	-50 +180
Breakdown voltage	kV/mm	-
Volume resistance	0hm - cm	> 10^{13}

Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.